

## Features

- Three-State Outputs
- Separate Output Enable Inputs
- Fanout (Over Temperature Range)
  - Standard Outputs ..... 10 LSTTL Loads
  - Bus Driver Outputs ..... 15 LSTTL Loads
- Wide Operating Temperature Range ... -55°C to 125°C
- Balanced Propagation Delay and Transition Times
- Significant Power Reduction Compared to LSTTL Logic ICs
- HC Types
  - 2V to 6V Operation
  - High Noise Immunity:  $N_{IL} = 30\%$ ,  $N_{IH} = 30\%$  of  $V_{CC}$  at  $V_{CC} = 5V$
- HCT Types
  - 4.5V to 5.5V Operation
  - Direct LSTTL Input Logic Compatibility,  $V_{IL} = 0.8V$  (Max),  $V_{IH} = 2V$  (Min)
  - CMOS Input Compatibility,  $I_I \leq 1\mu A$  at  $V_{OL}, V_{OH}$

## Description

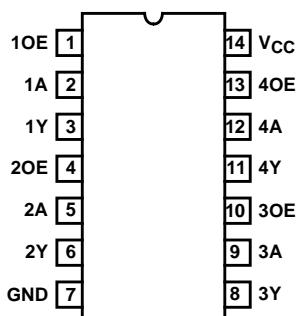
The 'HC126 and 'HCT126 contain four independent three-state buffers, each having its own output enable input, which when "low" puts the output in the high-impedance state.

## Ordering Information

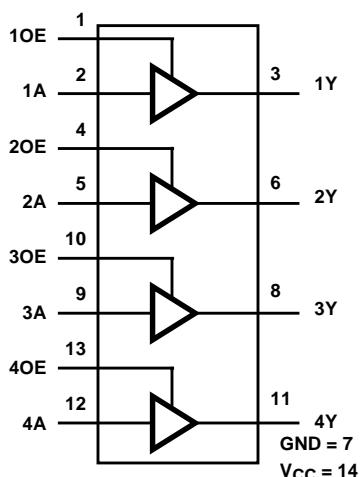
PART NUMBER	TEMP. RANGE (°C)	PACKAGE
CD54HC126F3A	-55 to 125	14 Ld CERDIP
CD54HCT126F3A	-55 to 125	14 Ld CERDIP
CD74HC126E	-55 to 125	14 Ld PDIP
CD74HC126M	-55 to 125	14 Ld SOIC
CD74HC126MT	-55 to 125	14 Ld SOIC
CD74HC126M96	-55 to 125	14 Ld SOIC
CD74HCT126E	-55 to 125	14 Ld PDIP
CD74HCT126M	-55 to 125	14 Ld SOIC
CD74HCT126MT	-55 to 125	14 Ld SOIC
CD74HCT126M96	-55 to 125	14 Ld SOIC

NOTE: When ordering, use the entire part number. The suffix 96 denotes tape and reel. The suffix T denotes a small-quantity reel of 250.

## Pinout

**CD54HC126, CD54HC126**
**(CERDIP)**
**CD74HC126, CD74HC126**
**(PDIP, SOIC)**
**TOP VIEW**


### Functional Diagram



TRUTH TABLE

INPUTS		OUTPUTS
nA	nOE	nY
H	H	H
L	H	L
X	L	Z

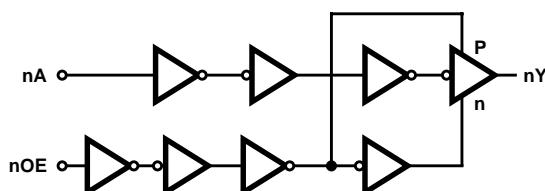
H= High Voltage Level

L= Low Voltage Level

X= Don't Care

Z= High Impedance, OFF State

### Logic Diagram



# CD54HC126, CD74HC126, CD54HCT126, CD74HCT126

## Absolute Maximum Ratings

DC Supply Voltage, V <sub>CC</sub>	.....	-0.5V to 7V
DC Input Diode Current, I <sub>IK</sub>		
For V <sub>I</sub> < -0.5V or V <sub>I</sub> > V <sub>CC</sub> + 0.5V	.....	±20mA
DC Output Diode Current, I <sub>OK</sub>		
For V <sub>O</sub> < -0.5V or V <sub>O</sub> > V <sub>CC</sub> + 0.5V	.....	±20mA
DC Drain Current, per Output, I <sub>O</sub>		
For -0.5V < V <sub>O</sub> < V <sub>CC</sub> + 0.5V	.....	±35mA
DC Output Source or Sink Current per Output Pin, I <sub>O</sub>		
For V <sub>O</sub> > -0.5V or V <sub>O</sub> < V <sub>CC</sub> + 0.5V	.....	±25mA
DC V <sub>CC</sub> or Ground Current, I <sub>CC</sub>	.....	±70mA

## Thermal Information

Thermal Resistance (Typical, Note 1)	θ <sub>JA</sub> (°C/W)
E (PDIP) Package	.....
M (SOIC) Package	.....
Maximum Junction Temperature	..... 150°C
Maximum Storage Temperature Range	..... -65°C to 150°C
Maximum Lead Temperature (Soldering 10s)	..... 300°C
(SOIC - Lead Tips Only)	

## Operating Conditions

Temperature Range (T <sub>A</sub> )	.....	-55°C to 125°C
Supply Voltage Range, V <sub>CC</sub>		
HC Types	.....	.2V to 6V
HCT Types	.....	.4.5V to 5.5V
DC Input or Output Voltage, V <sub>I</sub> , V <sub>O</sub>	.....	0V to V <sub>CC</sub>
Input Rise and Fall Time		
2V	.....	1000ns (Max)
4.5V	.....	500ns (Max)
6V	.....	400ns (Max)

**CAUTION:** Stresses above those listed in "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress only rating and operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied.

### NOTE:

1. The package thermal impedance is calculated in accordance with JESD 51-7.

## DC Electrical Specifications

PARAMETER	SYMBOL	TEST CONDITIONS		V <sub>CC</sub> (V)	25°C			-40°C TO 85°C		-55°C TO 125°C		UNITS
		V <sub>I</sub> (V)	I <sub>O</sub> (mA)		MIN	TYP	MAX	MIN	MAX	MIN	MAX	
<b>HC TYPES</b>												
High Level Input Voltage	V <sub>IH</sub>	-	-	2	1.5	-	-	1.5	-	1.5	-	V
				4.5	3.15	-	-	3.15	-	3.15	-	V
				6	4.2	-	-	4.2	-	4.2	-	V
Low Level Input Voltage	V <sub>IL</sub>	-	-	2	-	-	0.5	-	0.5	-	0.5	V
				4.5	-	-	1.35	-	1.35	-	1.35	V
				6	-	-	1.8	-	1.8	-	1.8	V
High Level Output Voltage CMOS Loads	V <sub>OH</sub>	V <sub>IH</sub> or V <sub>IL</sub>	-0.02	2	1.9	-	-	1.9	-	1.9	-	V
			-0.02	4.5	4.4	-	-	4.4	-	4.4	-	V
			-0.02	6	5.9	-	-	5.9	-	5.9	-	V
High Level Output Voltage TTL Loads			-6	4.5	3.98	-	-	3.84	-	3.7	-	V
			-7.8	6	5.48	-	-	5.34	-	5.2	-	V
Low Level Output Voltage CMOS Loads	V <sub>OL</sub>	V <sub>IH</sub> or V <sub>IL</sub>	0.02	2	-	-	0.1	-	0.1	-	0.1	V
			0.02	4.5	-	-	0.1	-	0.1	-	0.1	V
			0.02	6	-	-	0.1	-	0.1	-	0.1	V
Low Level Output Voltage TTL Loads			6	4.5	-	-	0.26	-	0.33	-	0.4	V
			7.8	6	-	-	0.26	-	0.33	-	0.4	V
Input Leakage Current	I <sub>I</sub>	V <sub>CC</sub> or GND	-	6	-	-	±0.1	-	±1	-	±1	µA

# CD54HC126, CD74HC126, CD54HCT126, CD74HCT126

## DC Electrical Specifications (Continued)

PARAMETER	SYMBOL	TEST CONDITIONS		V <sub>CC</sub> (V)	25°C			-40°C TO 85°C		-55°C TO 125°C		UNITS
		V <sub>I</sub> (V)	I <sub>O</sub> (mA)		MIN	TYP	MAX	MIN	MAX	MIN	MAX	
Quiescent Device Current	I <sub>CC</sub>	V <sub>CC</sub> or GND	0	6	-	-	8	-	80	-	160	µA
Three-State Leakage Current	I <sub>OZ</sub>	V <sub>IL</sub> or V <sub>IH</sub>	-	6	-	-	±0.5	-	±5	-	±10	µA
<b>HCT TYPES</b>												
High Level Input Voltage	V <sub>IH</sub>	-	-	4.5 to 5.5	2	-	-	2	-	2	-	V
Low Level Input Voltage	V <sub>IL</sub>	-	-	4.5 to 5.5	-	-	0.8	-	0.8	-	0.8	V
High Level Output Voltage CMOS Loads	V <sub>OH</sub>	V <sub>IH</sub> or V <sub>IL</sub>	-0.02	4.5	4.4	-	-	4.4	-	4.4	-	V
High Level Output Voltage TTL Loads			-6	4.5	3.98	-	-	3.84	-	3.7	-	V
Low Level Output Voltage CMOS Loads	V <sub>OL</sub>	V <sub>IH</sub> or V <sub>IL</sub>	0.02	4.5	-	-	0.1	-	0.1	-	0.1	V
Low Level Output Voltage TTL Loads			6	4.5	-	-	0.26	-	0.33	-	0.4	V
Input Leakage Current	I <sub>I</sub>	V <sub>CC</sub> to GND	0	5.5	-	-	±0.1	-	±1	-	±1	µA
Quiescent Device Current	I <sub>CC</sub>	V <sub>CC</sub> or GND	0	5.5	-	-	8	-	80	-	160	µA
Additional Quiescent Device Current Per Input Pin: 1 Unit Load	ΔI <sub>CC</sub> (Note 2)	V <sub>CC</sub> -2.1	-	4.5 to 5.5	-	100	360	-	450	-	490	µA
Three-State Leakage Current	I <sub>OZ</sub>	V <sub>IL</sub> or V <sub>IH</sub>	-	5.5	-	-	±0.5	-	±5	-	±10	µA

NOTE:

- For dual-supply systems theoretical worst case (V<sub>I</sub> = 2.4V, V<sub>CC</sub> = 5.5V) specification is 1.8mA.

## HCT Input Loading Table

INPUT	UNIT LOADS
nA, nOE	1

NOTE: Unit Load is ΔI<sub>CC</sub> limit specified in DC Electrical Specifications table, e.g., 360µA max at 25°C.

# CD54HC126, CD74HC126, CD54HCT126, CD74HCT126

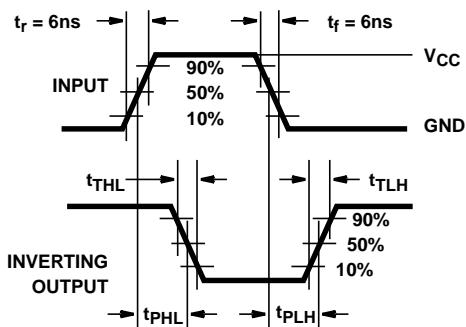
**Switching Specifications** Input  $t_r, t_f = 6\text{ns}$

PARAMETER	SYMBOL	TEST CONDITIONS	$V_{CC}$ (V)	25°C		-40°C TO 85°C	-55°C TO 125°C	UNITS
				TYP	MAX	MAX	MAX	
<b>HC TYPES</b>								
Propagation Delay Data to Outputs	$t_{PLH}, t_{PHL}$	$C_L = 50\text{pF}$	2	-	100	125	150	ns
			4.5	-	20	25	30	ns
		$C_L = 15\text{pF}$	5	8	-	-	-	ns
		$CL = 50\text{pF}$	6	-	17	21	36	ns
Enable Delay Time	$t_{PZL}, t_{PZH}$	$C_L = 50\text{pF}$	2	-	125	155	190	ns
			4.5	-	25	31	38	ns
		$C_L = 15\text{pF}$	5	10	-	-	-	ns
		$CL = 50\text{pF}$	6	-	21	26	32	ns
Disabling Delay Time	$t_{PLZ}, t_{PHZ}$	$CL = 50\text{pF}$	2	-	125	155	190	ns
		$C_L = 50\text{pF}$	4.5	-	25	31	38	ns
		$C_L = 15\text{pF}$	5	10	-	-	-	ns
		$CL = 50\text{pF}$	6	-	21	26	32	ns
Output Transition Times	$t_{TLH}, t_{THL}$	$C_L = 50\text{pF}$	2	-	60	75	90	ns
			4.5	-	12	15	18	ns
			6	-	10	13	15	ns
Input Capacitance	$C_I$	-	-	-	10	10	10	pF
Three-State Output Capacitance	$C_O$	-	-	-	20	20	20	pF
Power Dissipation Capacitance (Notes 3, 4)	$C_{PD}$	-	5	30	-	-	-	pF
<b>HCT TYPES</b>								
Propagation Delay Time to Outputs	$t_{PLH}, t_{PHL}$	$C_L = 50\text{pF}$	4.5	-	24	30	36	ns
		$C_L = 15\text{pF}$	5	9	-	-	-	ns
Output Enable Time	$t_{PZL}, t_{PZH}$	$C_L = 50\text{pF}$	4.5	-	25	31	38	ns
		$C_L = 15\text{pF}$	5	10	-	-	-	ns
Output Disabling Time	$t_{PLZ}, t_{PHZ}$	$C_L = 50\text{pF}$	4.5	-	28	35	42	ns
		$C_L = 15\text{pF}$	5	11	-	-	-	ns
Output Transition Times	$t_{TLH}, t_{THL}$	$C_L = 50\text{pF}$	4.5	-	12	15	18	ns
Input Capacitance	$C_I$	-	-	-	10	10	10	pF
Three-State Output Capacitance	$C_O$	-	-	-	20	20	20	pF
Power Dissipation Capacitance (Notes 3, 4)	$C_{PD}$	-	5	36	-	-	-	pF

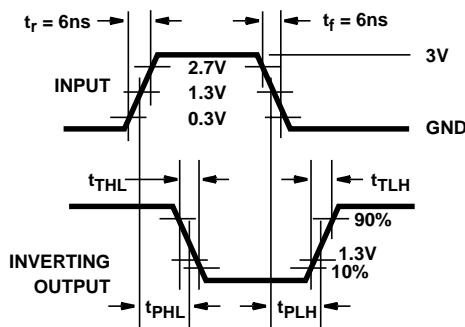
NOTES:

3.  $C_{PD}$  is used to determine the dynamic power consumption, per multiplexer.
4.  $P_D = V_{CC}^2 f_i (C_{PD} + C_L)$  where  $f_i$  = Input Frequency,  $C_L$  = Output Load Capacitance,  $V_{CC}$  = Supply Voltage.

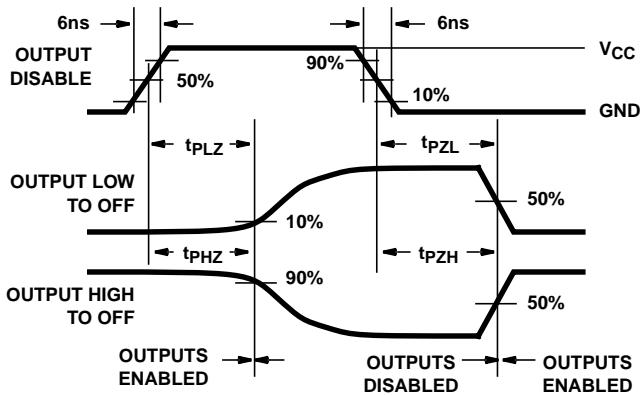
### Test Circuits and Waveforms



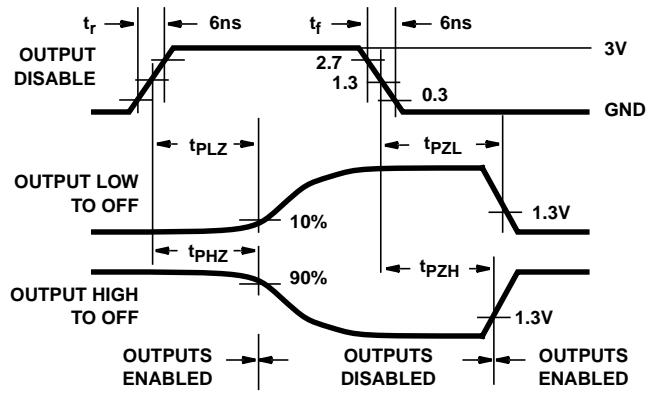
**FIGURE 6. HC TRANSITION TIMES AND PROPAGATION DELAY TIMES, COMBINATION LOGIC**



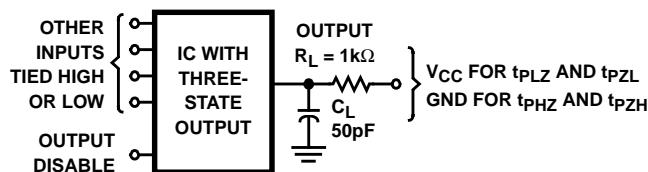
**FIGURE 7. HCT TRANSITION TIMES AND PROPAGATION DELAY TIMES, COMBINATION LOGIC**



**FIGURE 8. HC THREE-STATE PROPAGATION DELAY WAVEFORM**



**FIGURE 9. HCT THREE-STATE PROPAGATION DELAY WAVEFORM**



NOTE: Open drain waveforms  $t_{PLZ}$  and  $t_{PZL}$  are the same as those for three-state shown on the left. The test circuit is Output  $R_L = 1\text{k}\Omega$  to  $V_{CC}$ ,  $C_L = 50\text{pF}$ .

**FIGURE 10. HC AND HCT THREE-STATE PROPAGATION DELAY TEST CIRCUIT**